IRF9520

Vishay Siliconix



TO-220AB

PRODUCT SUMMARY

V_{DS} (V)

R_{DS(on)} (Ω)

Q_{qs} (nC)

Q_{gd} (nC)

Q_q max. (nC)

Configuration

G C

 $V_{GS} = -10 V$

P-Channel MOSFET

0.60

-100

18

3.0

9.0

Single

Power MOSFET

FEATURES

- Dynamic dv/dt rating
- Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF9520PbF
Lead (Pb)-free and halogen-free	IRF9520PbF-BE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	e noted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	-100	V	
Gate-source voltage			V _{GS}	± 20	v
Continuous drain current	V + 10 V	$T_C = 25 \ ^\circ C$ $T_C = 100 \ ^\circ C$	I _D	-6.8	
	V _{GS} at 10 V	T _C = 100 °C		-4.8	А
Pulsed drain current ^a		I _{DM}	-27		
Linear derating factor			0.40	W/°C	
Single pulse avalanche energy ^b		E _{AS}	300	mJ	
Repetitive avalanche current ^a		I _{AR}	-6.8	А	
Repetitive avalanche energy ^a			E _{AR}	6.0	mJ
Maximum power dissipation	T _C = 25 °C		PD	60	W
Peak diode recovery dV/dt ^c			dv/dt	-5.5	V/ns
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) ^d	For 10 s			300	
Mounting torque	6-32 or M3 screw			10	lbf ∙ in
Mounting torque				1.1	N · m

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. $V_{DD} = -25 \text{ V}$, starting $T_J = 25 \text{ °C}$, L = 9.7 mH, $R_g = 25 \Omega$, $I_{AS} = -6.8 \text{ A}$ (see fig. 12)

c.
$$I_{SD} \leq$$
 -6.8 A, di/dt \leq 110 A/µs, $V_{DD} \leq V_{DS}$, $T_J \leq$ 175 °C

d. 1.6 mm from case

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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	62	
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	2.5	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0$	Ο V, I _D = -250 μΑ	-100	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Reference	to 25 °C, I _D = -1 mA	-	-0.10	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V$	/ _{GS} , I _D = -250 μΑ	-2.0	-	-4.0	V
Gate-source leakage	I _{GSS}	V	_{GS} = ± 20 V	-	-	± 100	nA
	1	V _{DS} = -	100 V, V _{GS} = 0 V	-	-	-100	μA
Zero gate voltage drain current	IDSS	V _{DS} = -80 V,	V _{GS} = 0 V, T _J = 150 °C	-	-	-500	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = -10 V	I _D = -4.1 A ^b	-	-	0.60	Ω
Forward transconductance	9 _{fs}	V _{DS} = -{	50 V, I _D = -4.1 A ^b	2.0	-	-	S
Dynamic		•					
Input capacitance	C _{iss}	,	$V_{GS} = 0 V,$	-	390	-	
Output capacitance	C _{oss}	V	DS = -25 V,	-	170	-	pF
Reverse transfer capacitance	C _{rss}	f = 1.0	MHz, see fig. 5	-	45	-	1
Total gate charge	Qg			-	-	18	
Gate-source charge	Q _{gs}	V _{GS} = -10 V	I _D = -6.8 A, V _{DS} = -80 V, see fig. 6 and 13 ^b	-	-	3.0	nC
Gate-drain charge	Q _{gd}		see lig. 0 and 15	-	-	9.0	
Turn-on delay time	t _{d(on)}		•	-	9.6	-	
Rise time	t _r	V _{DD} = -	50 V, I _D = -6.8 A,	-	29	-	1
Turn-off delay time	t _{d(off)}	R _g = 18 Ω, R	$_{\rm D}$ = 7.1 Ω , see fig. 10 ^b	-	21	-	ns
Fall time	t _f			-	25	-	
Gate input resistance	R _g	f = 1 MHz, open drain		0.8	-	3.9	Ω
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	24
Internal source inductance	L _S			-	7.5	-	nH
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	I _S	MOSFET symb showing the		-	-	-6.8	- A
Pulsed diode forward current ^a	I _{SM}	p - n junction diode		-	-	-27	
Body diode voltage	V _{SD}	T _J = 25 °C, I	$_{\rm S}$ = -6.8 A, V _{GS} = 0 V ^b	-	-	-6.3	V
Body diode reverse recovery time	t _{rr}		6 9 A dl/dt. 100 A/ h	-	98	200	ns
Body diode reverse recovery charge	Q _{rr}	$I_{\rm J} = 25^{-1}$ C, $I_{\rm F} =$	-6.8 A, dl/dt = 100 A/µs ^b	-	0.33	0.66	μC
Forward turn-on time	t _{on}	Intrinsic turi	n-on time is negligible (turr	on is dor	ninated b	y L _S and	L _D)

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. Pulse width \leq 300 µs; duty cycle \leq 2 %

2





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

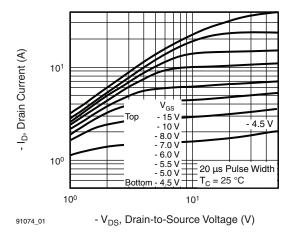


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

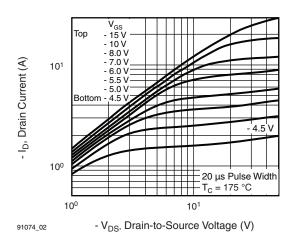


Fig. 2 - Typical Output Characteristics, T_C = 175 °C

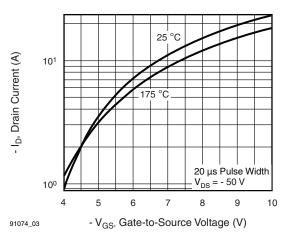


Fig. 3 - Typical Transfer Characteristics

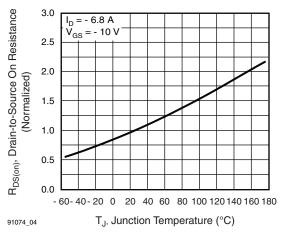


Fig. 4 - Normalized On-Resistance vs. Temperature

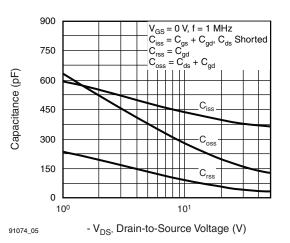


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

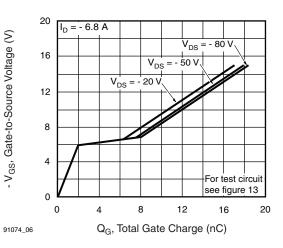


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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3 For technical questions, contact: <u>hvm@vishav.com</u> Document Number: 91074

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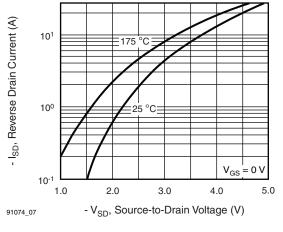


Fig. 7 - Typical Source-Drain Diode Forward Voltage

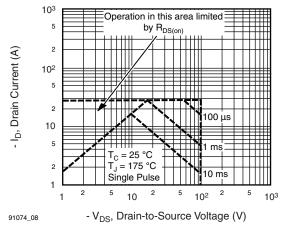


Fig. 8 - Maximum Safe Operating Area

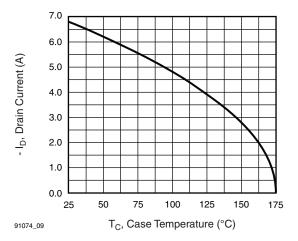


Fig. 9 - Maximum Drain Current vs. Case Temperature

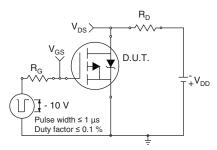


Fig. 10a - Switching Time Test Circuit

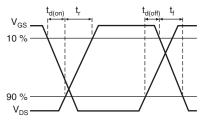
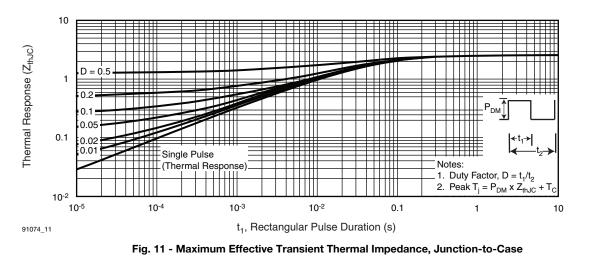


Fig. 10b - Switching Time Waveforms



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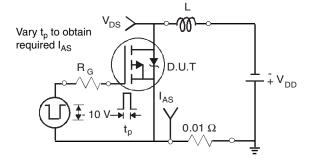


Fig. 12a - Unclamped Inductive Test Circuit

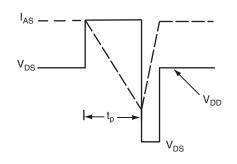


Fig. 12b - Unclamped Inductive Waveforms

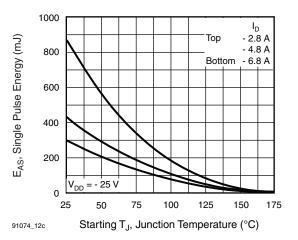


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

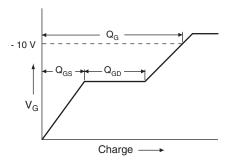


Fig. 13a - Basic Gate Charge Waveform

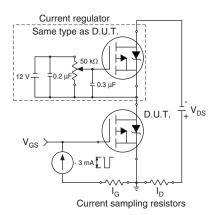
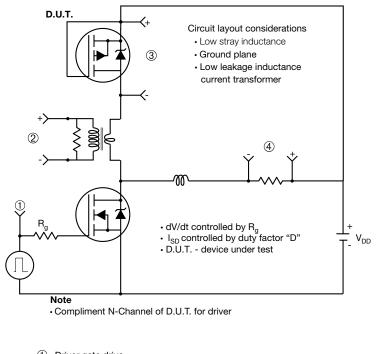


Fig. 13b - Gate Charge Test Circuit





Peak Diode Recovery dV/dt Test Circuit



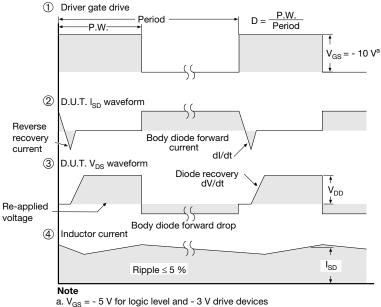


Fig. 14 - For P-Channel

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TO-220-1



DIM.	MILLIN	METERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
А	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØP	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

Note

• M* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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